

# RCX200N20

## Nch 200V 20A Power MOSFET

$V_{DSS}$	200V
R <sub>DS(on)</sub> (Max.)	130m $Ω$
I <sub>D</sub>	20A
$P_D$	48W

#### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

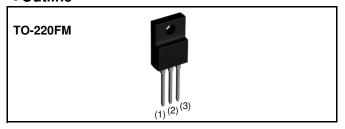
# Application

Switching Power Supply

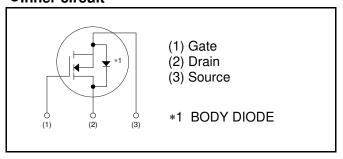
**Automotive Motor Drive** 

Automotive Solenoid Drive

#### Outline



## •Inner circuit



Packaging specifications

	Packaging	Bulk
	Reel size (mm)	-
Typo	Tape width (mm)	-
Туре	Quantity (pcs)	500
	Taping code	-
	Marking	RCX200N20

# ● Absolute maximum ratings(T<sub>a</sub> = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	200	V
Continuous drain current	$T_c = 25^{\circ}C$	I <sub>D</sub> *1	±20	А
	$T_c = 100$ °C	I <sub>D</sub> *1	±10.8	А
Pulsed drain current	I <sub>D,pulse</sub> *2	±80	А	
Gate - Source voltage	$V_{GSS}$	±30	V	
Avalanche energy, single pulse		E <sub>AS</sub> *3	32.3	mJ
Avalanche current		I <sub>AR</sub> *3	10	Α
$T_c = 25^{\circ}C$		P <sub>D</sub>	48	W
Power dissipation $T_a = 25^{\circ}C$		P <sub>D</sub>	2.23	W
Junction temperature		T <sub>j</sub>	150	°C
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C	

## ●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Utill
Thermal resistance, junction - case	$R_{thJC}$	-	-	2.57	°C/W
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	56	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# • Electrical characteristics $(T_a = 25^{\circ}C)$

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	200	-	-	V
		$V_{DS} = 200V, V_{GS} = 0V$			25	
Zara gata valtaga drain aurrent		$T_j = 25^{\circ}C$	-	-	25	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 200V, V_{GS} = 0V$	-		100	
		T <sub>j</sub> = 125°C		-		
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, \ V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	$V_{GS\ (th)}$	$V_{DS} = 10V$ , $I_D = 1mA$	3.0	-	5.0	V
		$V_{GS} = 10V, I_D = 10A$	-	100	130	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	$V_{GS} = 10V, I_D = 10A$		000	0.1.0	mΩ
		T <sub>j</sub> = 125°C	_	220	310	
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 10A$	4.9	9.8	-	S

# • Electrical characteristics ( $T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
r arameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	ı	1900	ı	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	120	1	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	70	1	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 100V, V_{GS} = 10V$	-	35	1	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 10A	-	100	1	ne
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L = 10\Omega$	-	60	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	45	-	

# •Gate Charge characteristics( $T_a = 25$ °C)

Dorometer	Cumbal	Conditions	Values			Lloit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{^{*4}}$	$V_{DD} \simeq 100V$	-	40	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 10A	-	15	-	nC
Gate - Drain charge	${\sf Q_{gd}}^{^{*4}}$	$V_{GS} = 10V$	-	15	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} \simeq 100V, I_D = 10A$	-	8.0	-	V

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Cymbol	Conditions	Values			Unit
- Farameter	Parameter Symbol		Min.	Тур.	Max.	Offic
Continuous source current	l <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	ı	20	Α
Pulsed source current	I <sub>SM</sub> *2	1 <sub>c</sub> = 23 0	-	-	80	Α
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = 10A	-	100	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	350	-	nC

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\simeq}$  500 $\mu$ H,  $V_{DD}$  = 50V, Rg = 25 $\Omega$ , starting  $T_j$  = 25°C

<sup>\*4</sup> Pulsed

Fig.1 Power Dissipation Derating Curve

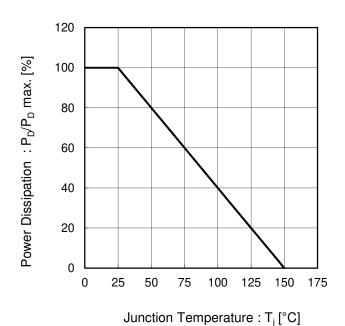
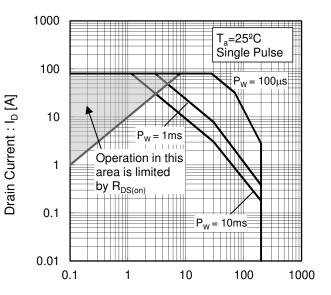
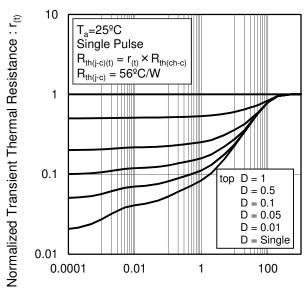


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw[s]

Fig.4 Avalanche Current vs Inductive Load

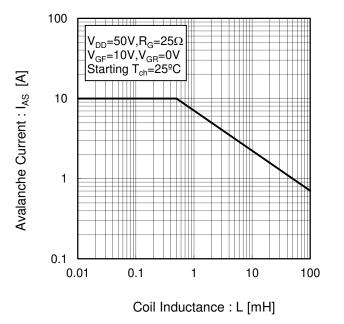
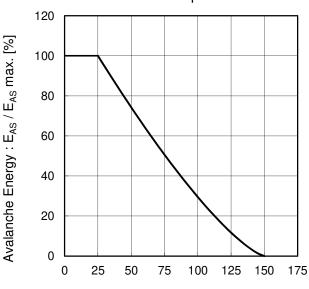
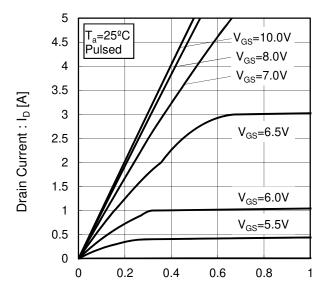


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



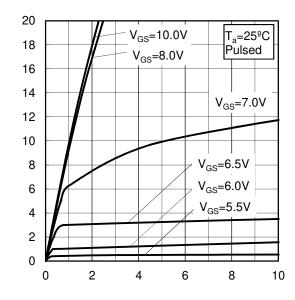
Junction Temperature : T<sub>i</sub> [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage :  $V_{DS}\left[V\right]$ 

Fig.7 Typical Output Characteristics(II)

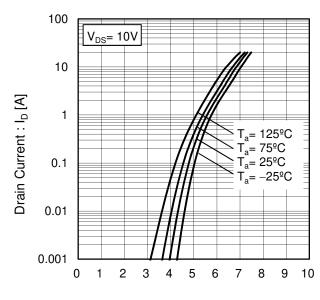


Drain - Source Voltage : V<sub>DS</sub> [V]

Drain Current: I<sub>D</sub> [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage  $V_{GS} = 0V$ 270  $I_D = 1mA$ 260 250 240 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T<sub>i</sub> [°C]

Fig.9 Typical Transfer Characteristics



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature

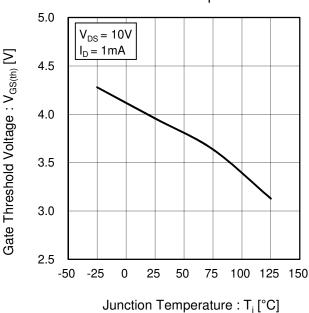
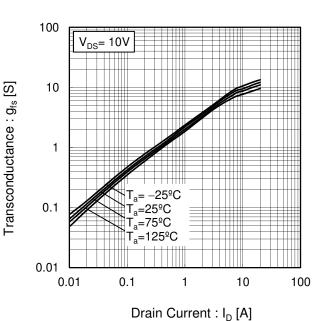


Fig.11 Transconductance vs. Drain Current



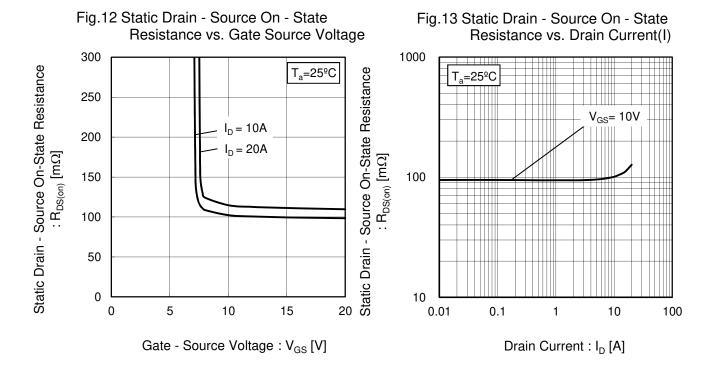


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

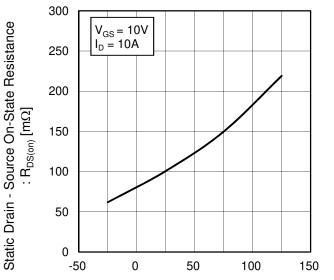


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

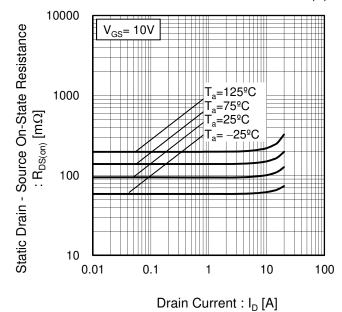


Fig.16 Drain Current Derating Curve

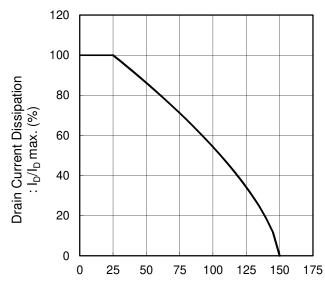
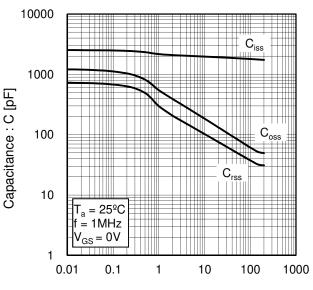


Fig.17 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.18 Switching Characteristics

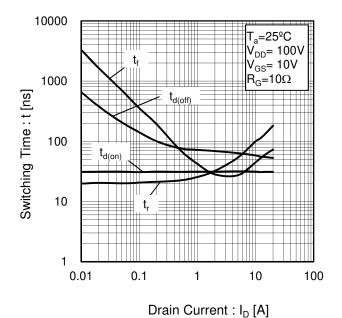
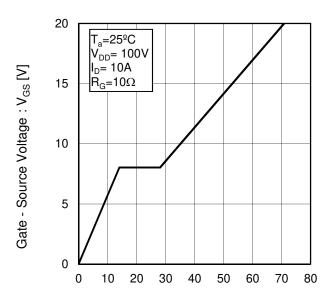


Fig.19 Dynamic Input Characteristics



Total Gate Charge :  $Q_g$  [nC]

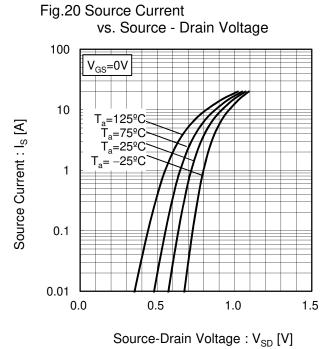


Fig21 Reverse Recovery Time
vs. Source Current

1000

Ta=25°C
di / dt = 100A / µs
VGS = 0V

100
0.1 1 10 100

Source Current : I<sub>S</sub> [A]

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

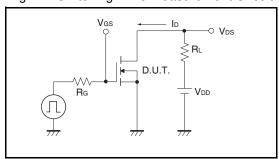


Fig.2-1 Gate Charge Measurement Circuit

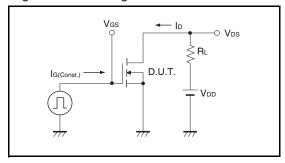


Fig.3-1 Avalanche Measurement Circuit

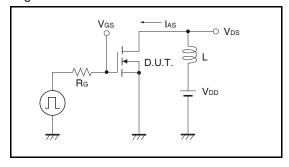


Fig.1-2 Switching Waveforms

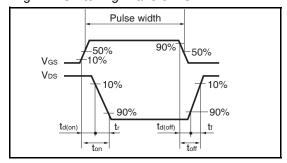


Fig.2-2 Gate Charge Waveform

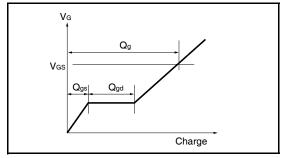
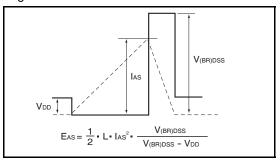
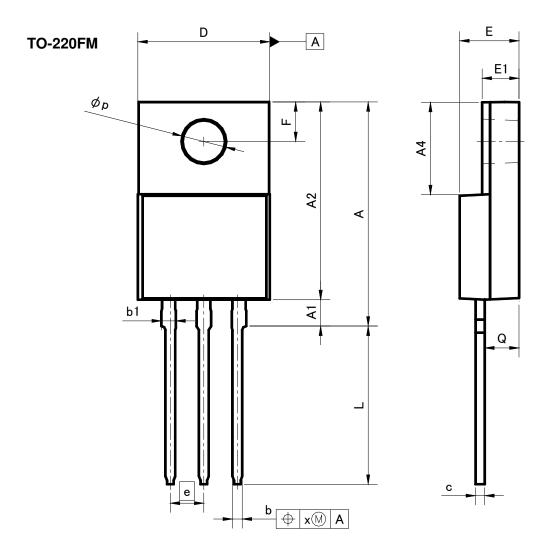


Fig.3-2 Avalanche Waveform



# ● **Dimensions** (Unit: mm)



DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.85	0.028	0.033
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.39	0.406
Е	4.40	4.80	0.173	0.189
е	2.54		0.	10
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.11	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
Х	_	0.381	_	0.015

Dimension in mm/inches

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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